

SCES050O-AUGUST 1995-REVISED SEPTEMBER 2004

#### **FEATURES**

- Member of the Texas Instruments Widebus™
   Family
- Operates From 1.65 V to 3.6 V
- Max t<sub>nd</sub> of 5.2 ns at 3.3 V
- ±24-mA Output Drive at 3.3 V
- All Outputs Have Equivalent 26- $\Omega$  Series Resistors, So No External Resistors Are Required
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)

#### **DESCRIPTION/ORDERING INFORMATION**

This 12-bit to 24-bit registered bus exchanger is designed for 1.65-V to 3.6-V  $V_{\rm CC}$  operation.

The SN74ALVCHR16269A is used in applications in which two ports must be multiplexed onto, or demultiplexed from, a single port. It is particularly suitable as an interface between synchronous DRAMs and high-speed microprocessors.

Data is stored in the internal B-port registers on the low-to-high transition of the clock (CLK) input, when the appropriate clock-enable (CLKENA) inputs are low. Proper control of these inputs allows two sequential 12-bit words to be presented as a 24-bit word on the B port. For data transfer in the B-to-A

# DGG, DGV, OR DL PACKAGE (TOP VIEW)



NC - No internal connection

direction, a single storage register is provided. The select (SEL) line selects 1B or 2B data for the A outputs. The register on the A output permits the fastest possible data transfer, thus extending the period during which the data is valid on the bus. The control terminals are registered so that all transactions are synchronous with CLK. Data flow is controlled by the active-low output enables (OEA, OEB1, and OEB2).

#### ORDERING INFORMATION

T <sub>A</sub>	PACK	AGE <sup>(1)</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	SSOP – DL	Tube	SN74ALVCHR16269AL	ALVCHR16269A
4000 1- 0500	330F - DL	Tape and reel	SN74ALVCHR16269ALR	ALVORK 10209A
-40°C to 85°C	TSSOP - DGG	Tape and reel	SN74ALVCHR16269AGR	ALVCHR16269A
	TVSOP - DGV	Tape and reel	SN74ALVCHR16269AVR	VR269A

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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## **DESCRIPTION/ORDERING INFORMATION (CONTINUED)**

To ensure the high-impedance state during power up or power down, a clock pulse should be applied as soon as possible, and  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver. Due to  $\overline{OE}$  being routed through a register, the active state of the outputs cannot be determined prior to the arrival of the first clock pulse.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

All outputs are designed to sink up to 12 mA and include equivalent 26- $\Omega$  resistors to reduce overshoot and undershoot.

#### **FUNCTION TABLES**

#### **OUTPUT ENABLE**

	INPUTS	OUTPUTS			
CLK	OEA	OEB	Α	1B, 2B	
1	Н	Н	Z	Z	
1	Н	L	Z	Active	
1	L	Н	Active	Z	
1	L	L	Active	Active	

## A-TO-B STORAGE (OEB = L)

	INPUTS		0	OUTI	PUTS
CLKENA1	CLKENA2	CLK	Α	1B	2B
L	Н	1	L	L	2B <sub>0</sub> <sup>(1)</sup>
L	Н	1	Н	Н	$2B_0^{(1)}$
L	L	$\uparrow$	L	L	L
L	L	$\uparrow$	Н	Н	Н
Н	L	$\uparrow$	L	1B <sub>0</sub> <sup>(1)</sup>	L
Н	L	$\uparrow$	Н	1B <sub>0</sub> <sup>(1)</sup>	Н
Н	Н	Χ	Х	1B <sub>0</sub> <sup>(1)</sup>	$2B_0^{(1)}$

 Output level before the indicated steady-state input conditions were established

## B-TO-A STORAGE ( $\overline{OEA} = L$ )

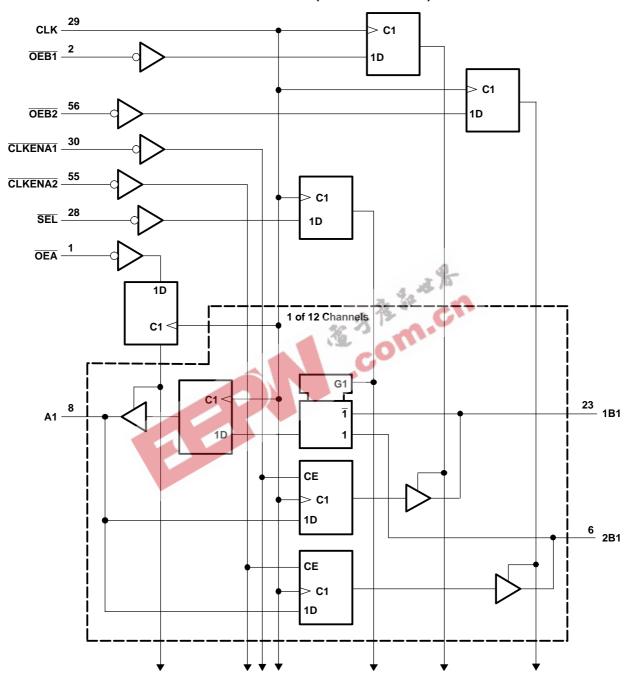
	INP	OUTPUT		
CLK	SEL	1B	2B	Α
Х	Н	Χ	Χ	A <sub>0</sub> <sup>(1)</sup>
X	L	Χ	Χ	A <sub>0</sub> <sup>(1)</sup> A <sub>0</sub> <sup>(1)</sup>
1	Н	L	Χ	L
1	Н	Н	Χ	Н
1	L	Χ	L	L
1	L	Х	Н	Н

 Output level before the indicated steady-state input conditions were established



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## **LOGIC DIAGRAM (POSITIVE LOGIC)**





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# ABSOLUTE MAXIMUM RATINGS(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT	
V <sub>CC</sub>	Supply voltage range		-0.5	4.6	V	
,,	land the state of	Except I/O ports <sup>(2)</sup>	-0.5	4.6	W	
V <sub>I</sub>	Input voltage range	I/O ports <sup>(2)(3)</sup>	-0.5	V <sub>CC</sub> + 0.5	V	
Vo	Output voltage range <sup>(2)(3)</sup>	·		V <sub>CC</sub> + 0.5	V	
I <sub>IK</sub>	Input clamp current	V <sub>1</sub> < 0		-50	mA	
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0		-50	mA	
Io	Continuous output current			±50	mA	
	Continuous current through each V <sub>CC</sub> or GND	)		±100	mA	
		DGG package		64		
$\theta_{JA}$	Package thermal impedance (4)	DGV package		48	48 °C/W	
		DL package		56		
T <sub>stg</sub>	Storage temperature range		-65	150	°C	

<sup>(1)</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) This value is limited to 4.6 V, maximum.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.

## RECOMMENDED OPERATING CONDITIONS(1)

			MIN	MAX	UNIT	
V <sub>CC</sub>	Supply voltage		1.65	3.6	V	
		V <sub>CC</sub> = 1.65 V to 1.95 V	$0.65 \times V_{CC}$			
V <sub>IH</sub>	High-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2			
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$		$0.35 \times V_{CC}$		
$V_{IL}$	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		0.8		
V <sub>I</sub>	Input voltage		0	V <sub>cc</sub>	V	
Vo	Output voltage		0	V <sub>cc</sub>	V	
		V <sub>CC</sub> = 1.65 V		-2		
	High level output ourrent	V <sub>CC</sub> = 2.3 V		-6	mA	
I <sub>OH</sub>	High-level output current	$V_{CC} = 2.7 \text{ V}$		-8		
		V <sub>CC</sub> = 3 V		-12		
		V <sub>CC</sub> = 1.65 V		2		
	Low-level output current	V <sub>CC</sub> = 2.3 V		6	mA	
I <sub>OL</sub>	Low-level output current	$V_{CC} = 2.7 \text{ V}$		8	IIIA	
		V <sub>CC</sub> = 3 V		12		
Δt/Δν	Input transition rise or fall rate			10	ns/V	
T <sub>A</sub>	Operating free-air temperature		-40	85	°C	

<sup>(1)</sup> All unused control inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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## **ELECTRICAL CHARACTERISTICS**

over recommended operating free-air temperature range (unless otherwise noted)

PA	RAMETER	TEST CONDITIONS	V <sub>cc</sub>	MIN	TYP <sup>(1)</sup>	XAN	UNIT
		I <sub>OH</sub> = -100 μA	1.65 V to 3.6 V	V <sub>CC</sub> - 0.2			
		I <sub>OH</sub> = -2 mA	1.65 V	1.2			
		$I_{OH} = -4 \text{ mA}$	2.3 V	1.9			
V <sub>OH</sub>		I <sub>OH</sub> = -6 mA	2.3 V	1.7			V
		10H = -0 111A	3 V	2.4			
	PARAMETER  VOH  Vol  II  Ioz <sup>(3)</sup> Icc	I <sub>OH</sub> = -8 mA	2.7 V	2			
		I <sub>OH</sub> = -12 mA	3 V	2			
		$I_{OL} = 100 \mu\text{A}$	1.65 V to 3.6 V			0.2	
	$I_{OL} = 2 \text{ mA}$	1.65 V			0.45		
		$I_{OL} = 4 \text{ mA}$	2.3 V			0.4	
$V_{OL}$		I <sub>OL</sub> = 6 mA	2.3 V			0.55	V
		IOL - O IIIA	3 V			0.55	
		$I_{OL} = 8 \text{ mA}$	2.7 V			0.6	
		I <sub>OL</sub> = 12 mA	3 V 🐠			0.8	
I <sub>I</sub>		$V_I = V_{CC}$ or GND	3.6 V			±5	μΑ
		V <sub>I</sub> = 0.58 V	1.65 V	25			
		V <sub>I</sub> = 1.07 V	1.03	-25			
	V <sub>I</sub> = 0.7 V	2.3 V	45				
I <sub>I(hold)</sub>		V <sub>I</sub> = 1.7 V	2.5 V	-45			μΑ
		V <sub>I</sub> = 0.8 V	3 V	75			
		V <sub>I</sub> = 2 V	3 V	-75			
		$V_1 = 0 \text{ to } 3.6 \text{ V}^{(2)}$	3.6 V		=	±500	
I <sub>OZ</sub> (3)		$V_O = V_{CC}$ or GND	3.6 V			±10	μΑ
I <sub>CC</sub>		$V_I = V_{CC}$ or GND, $I_O = 0$	3.6 V			40	μΑ
$\Delta I_{CC}$		One input at V <sub>CC</sub> - 0.6 V, Other inputs at V <sub>CC</sub> or GND	3 V to 3.6 V			750	μΑ
$C_i$	Control inputs	$V_I = V_{CC}$ or GND	3.3 V		5		pF
$C_{io}$	A or B ports	$V_O = V_{CC}$ or GND	3.3 V		8.5		pF

<sup>(1)</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ . (2) This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

<sup>(3)</sup> For I/O ports, the parameter  $I_{OZ}$  includes the input leakage current.



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#### **TIMING REQUIREMENTS**

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

			V <sub>CC</sub> =	1.8 V	V <sub>CC</sub> = ± 0.2	2.5 V 2 V	V <sub>CC</sub> = 2.7 V			3.3 V 3 V	UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f <sub>clock</sub>	Clock freque	ency		(1)		95		115		135	MHz
t <sub>w</sub>	Pulse duration	on, CLK high or low	(1)		5.2		4.3		3.3		ns
		A data before CLK↑	(1)		1.4		1.4		1		
		B data before CLK↑	(1)		1.6		1.5		1.1		
t <sub>su</sub>	Setup time	SEL before CLK↑	(1)		0.8		1.1		1.3		ns
		CLKENA1 or CLKENA2 before CLK↑	(1)		0.8		1		0.8		
		OE before CLK↑	(1)		1.7		1.6		1.2		
	*	A data after CLK↑	(1)		0.9		0.9		1.2		
		B data after CLK↑	(1)		0.8		0.6		1		
t <sub>h</sub>	Hold time	SEL after CLK↑	(1)		1.1		0.8		1.7		ns
		CLKENA1 or CLKENA2 after CLK↑	(1)		1.4		1		1.6		
		OE after CLK↑	(1)		0.9	.0	0.8		1.2		
,		as not available at the time of publication.		a.	e noted	北方	n				
SWI	TCHING CHA	ARACTERISTICS	4	K 3	- 1	100					
over r	recommended o	perating free-air temperature range (	unless o	therwis	e noted	(see F	Figure 1	)			

<sup>(1)</sup> This information was not available at the time of publication.

#### **SWITCHING CHARACTERISTICS**

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)			1.8 V	V <sub>CC</sub> = ± 0.2	2.5 V 2 V	V <sub>CC</sub> =	2.7 V	V <sub>CC</sub> = ± 0.3	3.3 V 3 V	UNIT
	(INFOT)	(GOTFOT)	MIN	TYP	MIN	MAX	MIN	MAX	MIN	MAX	
f <sub>max</sub>			(1)		95		115		135		MHz
	CLK	В		(1)	2.3	7.7		6.9	2.2	5.8	no
t <sub>pd</sub>	CLN	A		(1)	1.9	6.4		5.8	2	5.2	ns
	CLK	В		(1)	2.5	7.7		6.9	2.3	5.8	20
t <sub>en</sub>		А		(1)	2.2	6.7		6	2.1	5.3	ns
	CLK	В		(1)	3.3	8.1		6.7	2.4	6	20
t <sub>dis</sub>	CLK	A		(1)	2.7	8		6.2	2.1	6	ns

<sup>(1)</sup> This information was not available at the time of publication.

#### **OPERATING CHARACTERISTICS**

 $T_A = 25^{\circ}C$ 

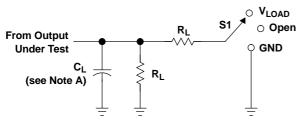
PARAMETER		TEST CONDITIONS	V <sub>CC</sub> = 1.8 V TYP	V <sub>CC</sub> = 2.5 V TYP	V <sub>CC</sub> = 3.3 V TYP	UNIT		
	Dower dissination consistence	Outputs enabled	$C_1 = 0, f = 10 \text{ MHz}$	(1)	142	172	٠,	
	Power dissipation capacitance	Outputs disabled	$C_L = 0, I = 10 \text{ MHz}$	(1)	115	129	pF	

<sup>(1)</sup> This information was not available at the time of publication.



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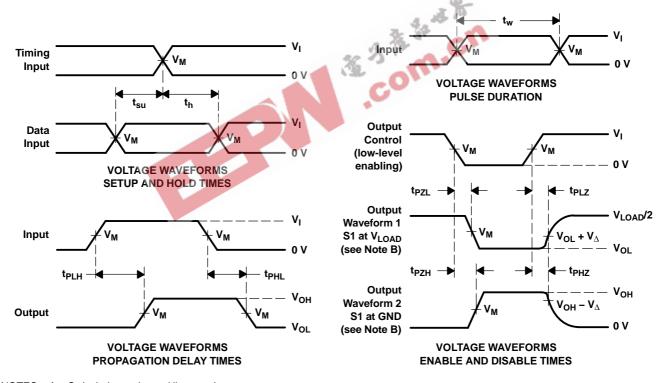
#### PARAMETER MEASUREMENT INFORMATION



TEST	S1
t <sub>pd</sub> t <sub>PLZ</sub> /t <sub>PZL</sub>	Open V <sub>LOAD</sub>
t <sub>PHZ</sub> /t <sub>PZH</sub>	GND

LOAD CIRCUIT

V	IN	PUT	V., V			В	V
V <sub>CC</sub>	VI	t <sub>r</sub> /t <sub>f</sub>	V <sub>M</sub>	V <sub>LOAD</sub>	CL	$R_L$	$V_{\Delta}$
1.8 V $\pm$ 0.15 V	V <sub>CC</sub>	≤2 ns	V <sub>CC</sub> /2	2×V <sub>CC</sub>	30 pF	<b>1 k</b> Ω	0.15 V
2.5 V $\pm$ 0.2 V	V <sub>CC</sub>	≤2 ns	V <sub>CC</sub> /2	2×V <sub>CC</sub>	30 pF	<b>500</b> Ω	0.15 V
2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	<b>500</b> Ω	0.3 V
3.3 V $\pm$ 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	<b>500</b> Ω	0.3 V



NOTES: A.  $C_L$  includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O$  = 50  $\Omega$ .
- D. The outputs are measured one at a time, with one transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



#### PACKAGE OPTION ADDENDUM

5-Sep-2005

#### **PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
74ALVCHR16269AGRE4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVCHR16269AVRE4	ACTIVE	TVSOP	DGV	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVCHR16269AGR	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVCHR16269AL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVCHR16269ALR	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVCHR16269AVR	ACTIVE	TVSOP	DGV	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>&</sup>lt;sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): Tl's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

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(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

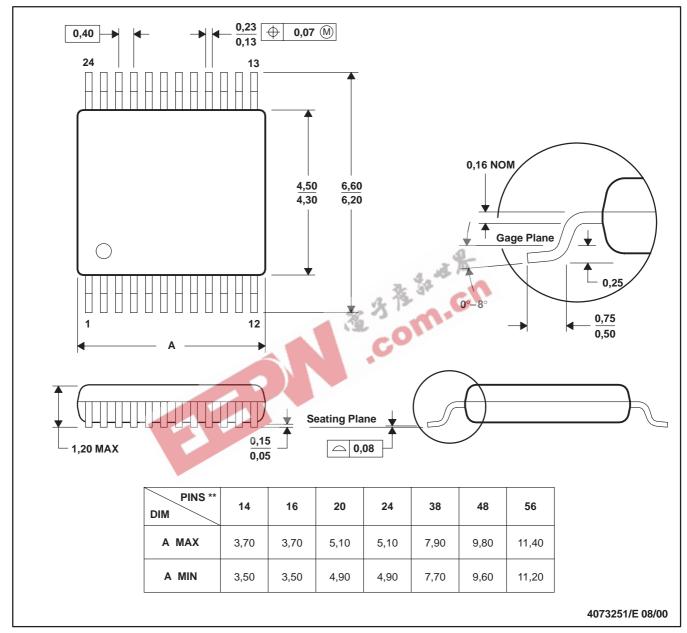
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## DGV (R-PDSO-G\*\*)

#### **24 PINS SHOWN**

#### **PLASTIC SMALL-OUTLINE**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

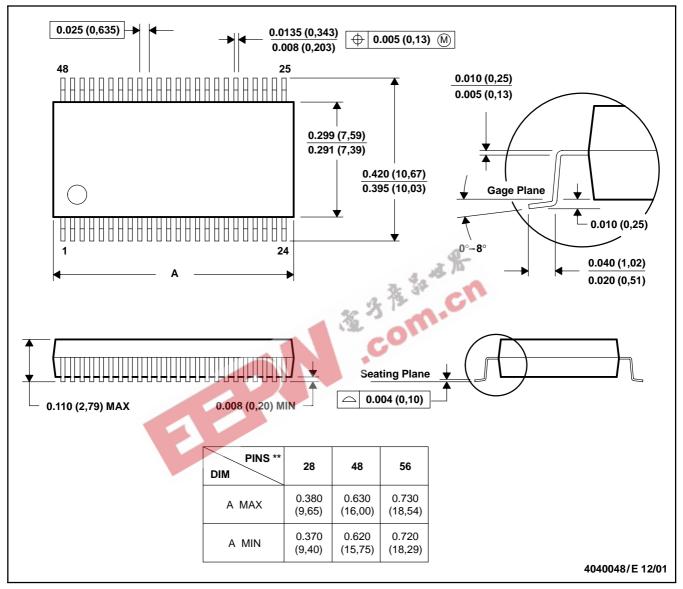
D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194



#### DL (R-PDSO-G\*\*)

#### PLASTIC SMALL-OUTLINE PACKAGE

#### **48 PINS SHOWN**



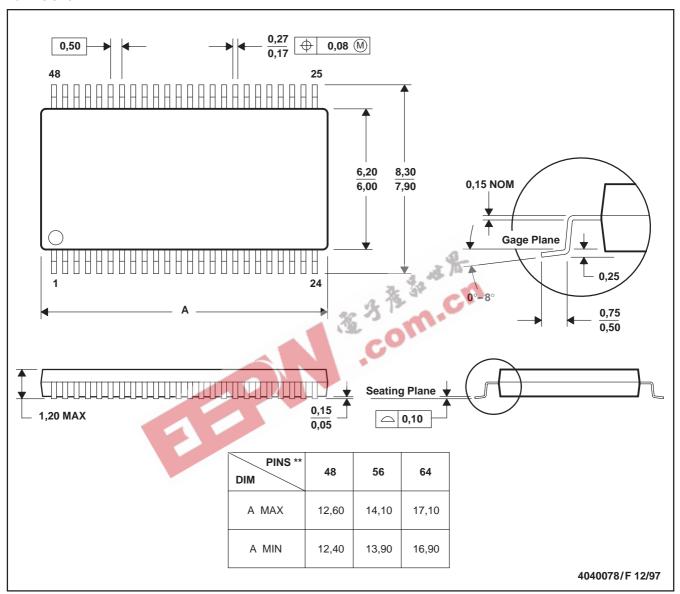
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

## DGG (R-PDSO-G\*\*)

#### PLASTIC SMALL-OUTLINE PACKAGE

#### **48 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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